Ordering number : ENA0858

LC87F76C8A

CMOSIC FROM 128K byte, RAM 4K byte on-chip 8-bit 1-chip Microcontroller



http://onsemi.com

Overview

The LC87F76C8A is an 8-bit microcomputer that, centered around a CPU running at a minimum bus cycle time of 83.3ns, integrates on a single chip a number of hardware features such as 128K-byte flash ROM (onboard programmable), 4K-byte RAM, an on-chip debugger, an LCD controller/driver, a sophisticated 16-bit timer/counter (may be divided into 8-bit timers), a 16-bit timer (may be divided into 8-bit timers or 8-bit PWMs), four 8-bit timers with a prescaler, a base timer serving as a time-of-day clock, a day and time counter, a synchronous SIO interface (with automatic block transmission/reception capabilities), an asynchronous/synchronous SIO interface, a UART interface (full duplex), a 8-bit 12-channel AD converter, two 12-bit PWM channels, a high-speed clock counter, a system clock frequency divider, a small signal detector, an infrared remote controller receiver function, and a 22source 10-vector interrupt feature.

Features

- ■Flash ROM
 - Capable of on-board-programming with a wide range of souce voltages: 3.0 to 5.5V.
 - Block-erasable in 2-byte units
 - 131072 × 8 bits (LC87F76C8A)

\blacksquare RAM

• 4096 × 9 bits (LC87F76C8A)

■Minimum Bus Cycle Time

• 83.3ns (12MHz) $V_{DD}=3.0 \text{ to } 5.5 \text{V}$ • 125ns (8MHz) $V_{DD}=2.5 \text{ to } 5.5 \text{V}$ • 250ns (4MHz) $V_{DD} = 2.2 \text{ to } 5.5 \text{ V}$

Note: The bus cycle time here refers to the ROM read speed.

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■Minimum Instruction Cycle Time (tCYC)

250ns (12MHz) V_{DD}=3.0 to 5.5V
 375ns (8MHz) V_{DD}=2.5 to 5.5V
 750ns (4MHz) V_{DD}=2.2 to 5.5V

■Ports

• Normal withstand voltage I/O ports

Ports whose I/O direction can be designated in 1-bit units 23 (P1n, P30 to P31, P70 to P73, P8n, XT2)

Ports whose I/O direction can be designated in 4-bit units 8 (P0n)

• Normal withstand voltage input port 1 (XT1)

• LCD ports

Segment output 32 (S00 to S31)
Common output 4 (COM0 to COM3)
Bias terminals for LCD driver 3 (V1 to V3)

Other functions

Input/output ports 32 (PAn, PBn, PCn, PDn,)

Input ports 7 (PLn)

• Dedicated oscillator ports 2 (CF1, CF2)

• Reset pins 1 (RES)

• Power pins 6 (V_{SS}1 to V_{SS}3, V_{DD}1 to V_{DD}3)

■LCD Controller

- 1) Seven display modes are available (static, 1/2, 1/3, 1/4 duty \times 1/2, 1/3 bias)
- 2) Segment output and common output can be switched to general-purpose input/output ports
- ■Small Signal Detection (MIC signals etc)
 - 1) Counts pulses with the level which is greater than a preset value
 - 2) 2-bit counter

■Timers

• Timer 0: 16-bit timer/counter with two capture registers.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with 8-bit capture registers) \times 2 channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with 8-bit capture registers)

+ 8-bit counter (with two 8-bit capture registers)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with 16-bit capture registers)

Mode 3: 16-bit counter (with 16-bit capture registers)

• Timer 1: 16-bit timer that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs)

+ 8-bit timer with an 8-bit prescaler (with toggle outputs)

Mode 1: 8-bit PWM with an 8-bit prescaler \times 2 channels

Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)

(toggle outputs also possible from the lower-order 8 bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)

(The lower-order 8 bits can be used as PWM.)

- Timer 4: 8-bit timer with a 6-bit prescaler
- Timer 5: 8-bit timer with a 6-bit prescaler
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle output)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle output)
- Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
- 2) Interrupts programmable in 5 different time schemes
- Day and time counter
 - 1) Used with a base timer, the day and time counter can be used as a 65000 day + minute + second counter.

■High-speed Clock Counter

- 1) Can count clocks with a maximum clock rate of 20MHz (at a main clock of 10MHz).
- 2) Can generate output real-time.

■SIO

- SIO0: 8-bit synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle = 4/3 tCYC)
 - 3) Automatic continuous data transmission (1 to 256 bits specifiable in 1-bit units, suspension and resumption of data transmission possible in 1-byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8-data bits, 1-stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8-data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8-data bits, stop detect)

■UART

- Full duplex
- 7/8/9 bit data bits selectable
- 1 stop bit (2-bit in continuous data transmission)
- Built-in baudrate generator
- * When using UART, set POLDDR (PODDR: Bit0) to "0"
- ■AD Converter: 12 bits × 12 channels
- ■PWM: Multi frequency 12-bit PWM × 2 channels
- ■Infrared Remote Control Receiver Circuit
 - 1) Noise reduction function
 - (Time constant of noise reduction filter: approx. 120µs, when selecting a 32.768kHz crystal oscillator as a reference clock.)
 - 2) X'tal HOLD mode cancellation function
- ■Watchdog Timer
 - External RC watchdog timer
 - Interrupt and reset signals selectable

■Clock Output Function

- 1) Can output selected oscillation clock 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 as system clock.
- 2) Can output the source oscillation clock for the sub clock.

■Interrupts

- 22 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/remote control receiver
4	0001BH	H or L	INT3/base timer
5	00023H	H or L	ТОН
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/UART1 transmit
9	00043H	H or L	ADC/MIC/T6/T7/PWM4, PWM5
10	0004BH	H or L	Port 0/T4/T5

- Priority levels X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.
- IFLG (List of interrupt source flag function)
 - 1) Shows a list of interrupt source flags that caused a branching to a particular vector address
- ■Subroutine Stack Levels: 2048 levels maximum (The stack is allocated in RAM.)
- ■High-speed Multiplication/Division Instructions

16 bits × 8 bits
24 bits × 16 bits
16 bits ÷ 8 bits
24 bits ÷ 16 bits
12 tCYC execution time)
24 bits ÷ 16 bits
12 tCYC execution time)
24 bits ÷ 16 bits
12 tCYC execution time)

■Oscillation Circuits

- RC oscillation circuit (internal): For system clock
- CF oscillation circuit: For system clock, with internal Rf and external Rd
- Crystal oscillation circuit: For low-speed system clock, with internal Rf and external Rd
- Multifrequency RC oscillation circuit (internal): For system clock
 - 1) Adjustable in $\pm 4\%$ (typ) increments from the selected center frequency.
 - 2) Measures the frequency of the source oscillation clock using the input signal from XT1 as the reference.

■System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2μs, 2.4μs, 4.8μs, 9.6μs, 19.2μs, 38.4μs, and 76.8μs (at a main clock rate of 10MHz).

■System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2µs, 2.4µs, 4.8µs, 9.6µs, 19.2µs, 38.4µs, and 76.8µs (at a main clock rate of 10MHz).

■System Clock Multiplier Function

 Allows the 2 or 3 times the clock frequency to be selected when the crystal oscillation output is used as the system clock.

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation. (Some parts of the serial transfer function stops operation.)
 - 1) Oscillation is not stopped automatically.
 - 2) Canceled by a system reset or occurrence of an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The CF, RC, X'tal, and multifrequency RC oscillators automatically stop operation.
 - 2) There are three ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Setting at least one of the INTO, INT1, and INT2, pins to the specified level
 - (3) Having an interrupt source established at port 0
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer and infrared remote controller circuit.
 - 1) The CF, RC, and multifrequency RC oscillators automatically stop operation
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are five ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Setting at least one of the INT0, INT1, and INT2 pins to the specified level
 - (3) Having an interrupt source established at port 0
 - (4) Having an interrupt source established in the base timer circuit
 - (5) Having an interrupt source established in the infrared remote control receiver circuit

■On-chip Debugger

• Supports software debugging with the IC mounted on the target board.

■Package Form

QIP80(14×14): Lead-free type
TQFP80J(12×12): Lead-free type

■Development Tools

• On-chip debugger: TCB87-TypeB + LC87F76C8A

■Flash ROM Programming Board

Package	Programming Boards
QIP80(14×14)	W87F71256QF
TQFP80J(12×12)	W87F71256SQ

■Flash ROM Programmer

Maker	Model	Supported Version (Note)	Device
Flash Support Group, Inc (Single)	AF9708/AF9709/AF9709B (including models manufactured by Ando Electric Co., Ltd.)		LC87F76C8A
Flash Support Group, Inc (Gang)	AF9723 (main unit) (including models manufactured by Ando Electric Co., Ltd.) AF9833 (unit)		LC87F76C8A
(Gang)	(including models manufactured by Ando Electric Co., Ltd.)		
SANYO	SKK(SANYO FWS)	Application Version: After 1.04 Chip Data Version: After 2.09	LC87F76C8A

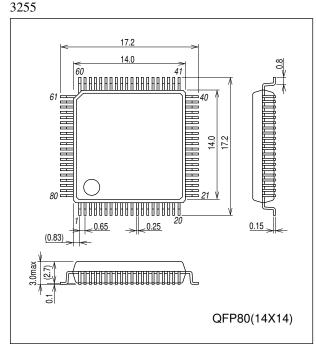
Note: Check for the latest version.

■Same Package and Pin Assignment as Mask ROM Version.

- 1) LC877600 series options can be specified by using flash ROM data. Thus the board used for mass production can be used for debugging and evaluation without modifications.
- 2) If the program for the mask ROM version is used, the size of the available ROM/RAM spaces is the same as that of the mask ROM version.

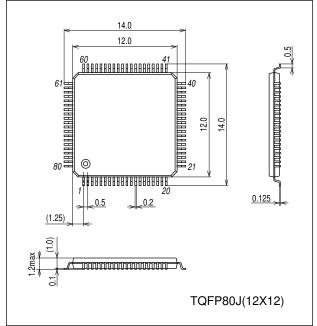
Package Dimensions

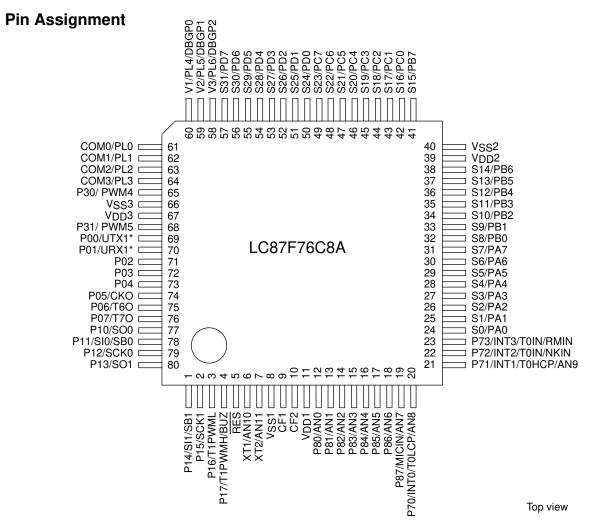
unit: mm (typ)



Package Dimensions

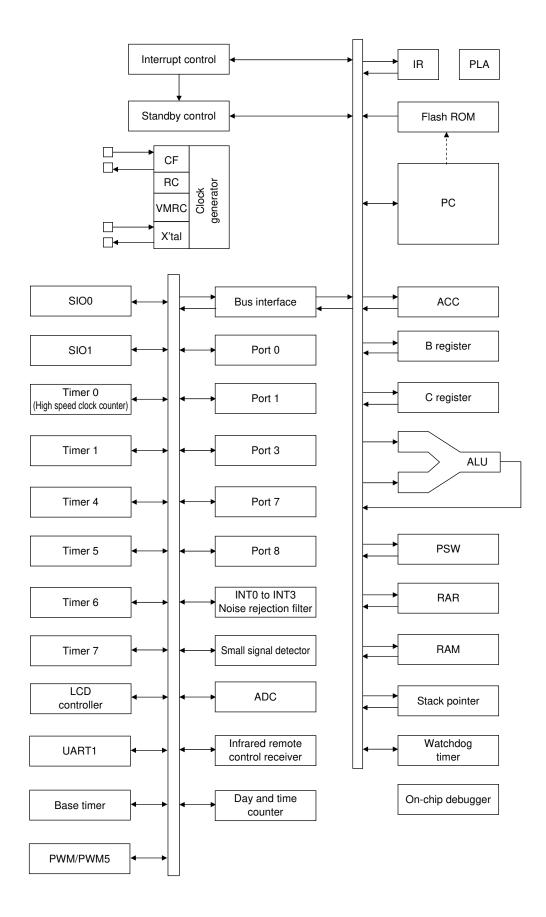
unit: mm (typ) 3290





*When using UART, set POLDDR (PODDR: Bit0) to "0" SANYO: QFP80(14×14) "Lead-free Type" SANYO: TQFP80J(12×12) "Lead-free Type"

System Block Diagram



Pin Description

Pin Name	I/O	Description					Option
V _{SS} 1	-	- power supply pin					No
V_{SS}^2							
V _{SS} 3							
V _{DD} 1	-	+ power supply pin					No
V _{DD} 2							
V _{DD} 3							
PORT0	I/O	8-bit I/O port		Yes			
P00 to P07	1	• I/O specifiable in 4-bit units					
		• Pull-up resistors can be turned on and off in 4-bit units.					
		Input for HOLD release					
		Input for port 0 interrupt					
		Shared pins					
		P00: UART1 transmit *					
		P01: UART1 receive *					
		P05: Clock output (system clock/subclock selectable)					
		P06: Timer 6 toggle output					
		P07: Timer 7 toggle output					
		* When using UART, set P0LDDR (PODDR: Bit0) to "0"					
PORT1	I/O	8-bit I/O port					Yes
P10 to P17		I/O specifiable in 1-bit units					
		 Pull-up resistors can be turned on and off in 1-bit units. 					
		Shared pins					
		P10: SIO0 data output					
		P11: SIO0 data input/bus I/O					
		P12: SIO0 clock I/O					
		P13: SIO1 data output					
		P14: SIO1 data input/bus I/O					
		P15: SIO1 clock I/O					
		P16: Timer 1 PWML output					
DODTO.	1/0	P17: Timer 1PWMH output/beeper output					
PORT3	I/O	• 2-bit I/O port					Yes
P30 to P31		• I/O specifiable in 1-bit units					
		Pull-up resistors can be turned on and off in 1-bit units.					
		Shared pins PROPERMAN putput					
		P30: PWM4 output					
DODT7	1/0	P31: PWM5 output					NI-
PORT7	I/O	• 4-bit I/O port					No
P70 to P73		I/O specifiable in 1-bit unitsPull-up resistors can be turned on and off in 1-bit units.					
		•					
		 Shared pins P70: INT0 input/HOLD release input/timer 0L capture in 	nut/watahda	a timor outn	+		
		P71: INT1 input/HOLD release input/timer 0L capture in	•	y timer outp	ut		
		P72: INT2 input/HOLD release input/timer 0 event input	-	nture innut/			
		high speed clock counter input	timer of oa	pture input			
		• .	er 0H cantu	re input/			
		P73: INT3 input (with noise filter)/timer 0 event input/timer 0H capture input/ infrared remote control receiver input					
		AD converter input ports: AN8 (P70), AN9 (P71)					
		Interrupt acknowledge type				_	
		Rising Falling Rising Fal	-	H level	L level		
			_	anal-1-	g.s.alali	1	
		INTO enable enable disa		enable	enable		
		INT1 enable enable disa		enable	enable		
		INT2 enable enable ena		disable	disable		
		INT3 enable enable ena	nie	disable	disable]	

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Pin Name	I/O	Description	Option
PORT8	I/O	• 8-bit I/O port	No
P80 to P87	1	• I/O specifiable in 1-bit units	
		Shared pins	
		AD converter input ports: AN0 to AN7	
		Small signal detector input port: MICIN (P87)	
S0/PA0 to	I/O	Segment output for LCD	No
S7/PA7		Can be used as general-purpose I/O port (PA)	
S8/PB0 to	I/O	Segment output for LCD	No
S15/PB7		Can be used as general-purpose I/O port (PB)	
S16/PC0 to	I/O	Segment output for LCD	No
S23/PC7		Can be used as general-purpose I/O port (PC)	
S24/PD0 to	I/O	Segment output for LCD	No
S31/PD7		Can be used as general-purpose I/O port (PD)	
COM0/PL0 to	I/O	Common output for LCD	No
COM3/PL3		Can be used as general-purpose input port (PL)	
V1/PL4 to	I/O	LCD drive bias power supply	No
V3/PL6		Can be used as general-purpose input port (PL)	
		Shared pins	
		On-chip debugger pins: DBGP0 (V1) to DBGP2 (V3)	
RES	Input	Reset pin	No
XT1	Input	32.768kHz crystal oscillator input pin	No
		Shared pins	
		General-purpose input port	
		Must be connected to V _{DD} 1 if not to be used.	
		AD converter input port: AN10	
XT2	I/O	32.768kHz crystal oscillator output pin	No
		Shared pins	
		General-purpose I/O port	
		Must be set for oscillation and kept open if not to be used.	
		AD converter input port: AN11	
CF1	Input	Ceramic resonator input pin	No
CF2	Output	Ceramic resonator output pin	No
		<u>I</u>	

Port Output Types

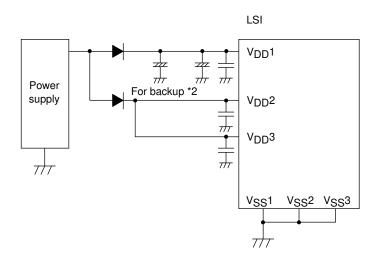
The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode.

Port Name	Option Selected in Units of	Option Type	Output Type	Pull-up Resistor
P00 to P07	each bit	1	CMOS	Programmable (Note)
		2	N-channel open drain	No
P10 to P17	each bit	1	CMOS	Programmable
		2	N-channel open drain	Programmable
P30 to P31	each bit	1	CMOS	Programmable
		2	N-channel open drain	Programmable
P70	-	No	N-channel open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
P80 to P87	-	No	N-channel open drain	No
S0/PA0 to S31/PD7	-	No	CMOS	Programmable
COM0/PL0 to COM3/PL3	-	No	Input only	No
V1/PL4 to V3/PL6	-	No	Input only	No
XT1	-	No	Input only	No
XT2	-	No	Output for 32.768kHz crystal oscillator (Nch-open drain when in general-purpose output mode)	No

Note: Programmable pull-up resistors for port 0 are controlled in 4 bit units (P00 to 03, P04 to 07).

*1 Connect the IC as shown below to minimize the noise input to the $V_{DD}1$ pin. Be sure to electrically short the $V_{SS}1$, $V_{SS}2$, and $V_{SS}3$ pins.



*2 The internal memory is sustained by V_{DD}1. If none of V_{DD}2 and V_{DD}3 are backed up, the high level output at the ports are unstable in the HOLD backup mode, allowing through current to flow into the input buffer and thus shortening the backup time.

Make sure that the port outputs are held at the low level in the HOLD backup mode.

Absolute Maximum Ratings at Ta = 25°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

	Davasatav	Oslr. s.l.	Dia/Damandra	O and distance		Specification		cation	
	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	ximum supply tage	V _{DD} max	$V_{DD}1, V_{DD}2, V_{DD}3$	V _{DD} 1=V _{DD} 2=V _{DD} 3		-0.3		+6.5	
Su _l LC	pply voltage for D	VLCD	V1/PL4, V2/PL5, V3/PL6	V _{DD} 1=V _{DD} 2=V _{DD} 3		-0.3		v _{DD}	
Inp	out voltage	V _I (1)	• Port L • XT1, CF1, RES			-0.3		V _{DD} +0.3	V
	out/output tage	V _{IO} (1)	• Ports 0, 1, 3, 7, 8 • Ports A, B, C, D • XT2			-0.3		V _{DD} +0.3	
	Peak output current	IOPH(1)	Ports 0, 1	CMOS output selected Per applicable pin		-10			
		IOPH(2)	Port 3	CMOS output selected Per applicable pin		-20			
		IOPH(3)	Ports 71 to 73	Per applicable pin		-5			
		IOPH(4)	Ports A, B, C, D	Per applicable pin		-5			
	Average output current	IOMH(1)	Ports 0, 1	CMOS output selected Per applicable pin		-7.5			
_	(Note 1-1)	IOMH(2)	Port 3	CMOS output selected Per applicable pin		-15			
rren		IOMH(3)	Ports 71 to 73	Per applicable pin		-3			
ıt cu		IOMH(4)	Ports A, B, C, D	Per applicable pin		-3			
High level output current	Total output	ΣΙΟΑΗ(1)	Ports 0, 1, 31	Total of currents at all applicable pins		-25			
igh leve	Carrent	ΣΙΟΑΗ(2)	Port 30	Total of currents at all applicable pins		-15			
I		ΣΙΟΑΗ(3)	Ports 0, 1, 3	Total of currents at all applicable pins		-40			
		ΣΙΟΑΗ(4)	Ports 71 to 73	Total of currents at all applicable pins		-5			mA
		ΣΙΟΑΗ(5)	Ports A, B	Total of currents at all applicable pins		-25			
		ΣΙΟΑΗ(6)	Ports C, D	Total of currents at all applicable pins		-25			
		ΣΙΟΑΗ(7)	Ports A, B, C, D	Total of currents at all applicable pins		-45			
\exists	Peak output	IOPL(1)	Ports 0, 1	Per applicable pin				20	
	current	IOPL(2)	Port 3	Per applicable pin				30	
Low level output current		IOPL(3)	• Ports 7, 8 • XT2	Per applicable pin				10	
tput (IOPL(4)	Ports A, B, C, D	Per applicable pin				10	
l out	Average	IOML(1)	Ports 0, 1	Per applicable pin				15	
leve	output current	IOML(2)	Port 3	Per applicable pin				20	
Low	(Note 1-1)	IOML(3)	• Ports 7, 8 • XT2	Per applicable pin				7.5	
		IOML(4)	Ports A, B, C, D	Per applicable pin				7.5	1

Note 1-1: Average output current refers to the average of output currents measured for a period of 100ms.

Continued on next page.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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	Parameter	Cumbal	Symbol Pin/Remarks	Conditions	Conditions	Specification				
	Parameter	Symbol		Conditions	V _{DD} [V]	min	typ	max	unit	
	Total output current	ΣIOAL(1)	Ports 0, 1, 31	Total of currents at all applicable pins				45		
t t		ΣIOAL(2)	Port 30	Total of currents at all applicable pins				45		
Low level output current		ΣIOAL(3)	Ports 0, 1, 3	Total of currents at all applicable pins				80		
ontbu		ΣIOAL(4)				20	mA			
ow leve		ΣIOAL(5)	Ports A, B	Total of currents at all applicable pins				45		
		ΣIOAL(6)	Ports C, D	Total of currents at all applicable pins				45		
		ΣIOAL(7)	Ports A, B, C, D	Total of currents at all applicable pins				80		
Ma	aximum power	Pd max	QFP80(14×14)	Ta=-20 to+70°C				290		
dis	ssipation		TQFP80J(12×12)						mW	
	perating ambient mperature	Topr				-20		+85		
	orage ambient mperature	Tstg				-55		+125	°C	

Note 1-1: Average output current refers to the average of output currents measured for a period of 100 ms.

Allowable Operating Range at $Ta = -20^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

	0	D' (D l .	0			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	V _{DD} 1=V _{DD} 2=V _{DD} 3	0-237μs≤tCYC≤200μs		3.0		5.5	
supply voltage	V _{DD} (2)		0-356μs≤tCYC≤200μs		2.5		5.5	
(Note 2-1)	V _{DD} (3)		0-712μs≤tCYC≤200μs		2.2		5.5	
Memory sustaining supply voltage	VHD	V _{DD} 1	RAM and register contents sustained in HOLD mode		2.0		5.5	
High level input voltage	V _{IH} (1)	• Ports 0, 3, 8 • Ports A, B, C, D • Port L	Output disabled	2.2 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (2)	Port 1 Ports 71 to 73 Port 70 port input/ interrupt side	Output disabled When INT1VTSL=0 (P71only)	2.2 to 5.5	0.3V _{DD} +0.7		V _{DD}	V
	V _{IH} (3)	Port 71 interrupt side	Output disabled When INT1VTSL=1	2.2 to 5.5	0.85V _{DD}		V _{DD}	
	V _{IH} (4)	Port 87 small signal input side	Output disabled	2.2 to 5.5	0.75V _{DD}		V _{DD}	
	V _{IH} (5)	Port 70 watchdog timer side	Output disabled	2.2 to 5.5	0.9V _{DD}		V _{DD}	
	V _{IH} (6)	XT1, XT2, CF1, RES		2.2 to 5.5	0.75V _{DD}		V_{DD}	

Note 2-1: V_{DD} must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

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Parameter	Symbol	Pin/Remarks	Conditions			Specific	cation	
				V _{DD} [V]	min	typ	max	unit
Low level input voltage	V _{IL} (1)	Ports 0, 3, 8Ports A, B, C, D	Output disabled	4.0 to 5.5	V _{SS}		0.15V _{DD} +0.4	
		• Port L		2.2 to 4.0	V_{SS}		0.2V _{DD}	
	VIL(2)	• Port 1 • Ports 71 to 73	Output disabled When INT1VTSL=0	4.0 to 5.5	V_{SS}		0.1V _{DD} +0.4	
		Port 70 port input/ interrupt side	(P71 only)	2.2 to 4.0	V _{SS}		0.2V _{DD}	٧
	V _{IL} (3)	Port 71 interrupt side	Output disabled When INT1VTSL=1	2.2 to 5.5	V _{SS}		0.45V _{DD}	v
	V _{IL} (4)	Port 87 small signal input side	Output disabled	2.2 to 5.5	V _{SS}		0.25V _{DD}	
	V _{IL} (5)	Port 70 watchdog timer side	Output disabled	2.2 to 5.5	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (6)	XT1, XT2, CF1, RES		2.2 to 5.5	V_{SS}		0.25V _{DD}	
Instruction cycle	tCYC			3.0 to 5.5	0.237		200	
time				2.5 to 5.5	0.356		200	μs
(Note 2-2)				2.2 to 5.5	0.712		200	
External system	FEXCF(1)	CF1	CF2 pin open	3.0 to 5.5	0.1		12	
clock frequency			System clock frequency	2.5 to 5.5	0.1		8	
			division ratio=1/1 • External system clock DUTY50±5%	2.2 to 5.5	0.1		4	
			• CF2 pin open	3.0 to 5.5	0.2		24.4	
			System clock frequency	2.5 to 5.5	0.2		16	
			division ratio=1/2	2.2 to 5.5	0.2		8	
Oscillation frequency range	FmCF(1)	CF1, CF2	12MHz ceramic oscillation See figure 1.	3.0 to 5.5	0.2	12	-	
(Note 2-3)	FmCF(2)	CF1, CF2	8MHz ceramic oscillation See figure 1.	2.5 to 5.5		8		
	FmCF(3)	CF1, CF2	4MHz ceramic oscillation See figure 1.	2.2 to 5.5		4		MHz
	FmRC		Internal RC oscillation	2.2 to 5.5	0.3	1.0	2.0	
	FmVMRC(1)		Multifrequency RC source oscillation VMRAJ2 to 0=4, VMFAJ2 to 0=0, When VMSL4M=0	2.2 to 5.5		10		
	FmVMRC(2)		Multifrequency RC source oscillation VMRAJ2 to 0=4, VMFAJ2 to 0=0, When VMSL4M=1	2.2 to 5.5		4		
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See figure 2.	2.2 to 5.5		32.768		kHz
Multifrequency	OpVMRC(1)		When VMSL4M=0	2.2 to 5.5	8	10	12	
RC oscillation usable range	OpVMRC(2)		When VMSL4M=1	2.2 to 5.5	3.5	4	4.5	MHz
Multifrequency	VmADJ(1)		VMRAJn 1STEP (Wide range)	2.2 to 5.5	8	24	64	
RC oscillation adjustment range	VmADJ(2)		VMFAJn 1STEP (Narrow range)	2.2 to 5.5	1	4	8	%

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Electrical Characteristics at $Ta = -20^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

		100.00 00 10	= = = = = = = = = = = = = = = = = = =	. 22-	. 225		ation	
Parameter	Symbol	Pin/Remarks	Conditions	\/ [\/]	min	Specifica		unit
High level input current	I _{IH} (1)	• Ports 0, 1, 3, 7, 8 • Ports A, B, C, D • Port L	Output disabled Pull-up resistor off VIN=VDD (including output Tr's)	V _{DD} [V]	min	typ	max 1	unit
			off leakage current)					
	I _{IH} (2)	RES	V _{IN} =V _{DD}	2.2 to 5.5			1	
	I _{IH} (3)	XT1, XT2	When configured as input ports VIN=VDD	2.2 to 5.5			1	
	I _{IH} (4)	CF1	V _{IN} =V _{DD}	2.2 to 5.5			15	
	I _{IH} (5)	Port 87 small signal	V _{IN} =VBIS+0.5V	4.5 to 5.5	4.2	8.5	15	
		input side	(VBIS denotes bias voltage)	2.2 to 4.5	1.5	5.5	10	_
Low level input current	I _{IL} (1)	• Ports 0, 1, 3, 7, 8 • Ports A, B, C, D • Port L	Output disabled Pull-up resistor off VIN=VSS (including output Tr's off leakage current)	2.2 to 5.5	-1			μА
	I _{IL} (2)	RES	V _{IN} =V _{SS}	2.2 to 5.5	-1			
	I _{IL} (3)	XT1, XT2	When configured as input ports VIN=VSS	2.2 to 5.5	-1			
	IIL(4)	CF1	V _{IN} =V _{SS}	2.2 to 5.5	-15			
	I _{IL} (5)	Port 87 small signal	V _{IN} =VBIS-0.5V	4.5 to 5.5	-15	-8.5	-4.2	
		input side	(VBIS denotes bias voltage)	2.2 to 4.5	-10	-5.5	-1.5	
High level output	V _{OH} (1)	CMOS output ports	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	0, 1	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.2mA	2.2 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	CMOS output ports	I _{OH} =-10mA	4.5 to 5.5	V _{DD} -1.5			
	V _{OH} (5)	30, 31	I _{OH} =-1.6mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (6)		I _{OH} =-1mA	2.2 to 5-5	V _{DD} -0.4			
	V _{OH} (7)	Ports 71 to 73	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (8)		I _{OH} =-0.2mA	2.2 to 5.5	V _{DD} -0.4			
	V _{OH} (9)	Ports A, B, C, D	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
	V _{OH} (10)		I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (11)		I _{OH} =-0.2mA	2.2 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	Ports 0, 1	I _{OL} =10mA	4.5 to 5.5			1.5	
voltage	V _{OL} (2)	• Port 3 (PWM4, 5	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (3)	function output mode)	I _{OL} =1mA	2.2 to 5.5			0.4	V
	V _{OL} (4)	Port 3	I _{OL} =30mA	4.5 to 5.5			1.5	V
	V _{OL} (5)	(Port function output	I _{OL} =5mA	3.0 to 5.5			0.4	
	V _{OL} (6)	mode)	I _{OL} =2.5mA	2.2 to 5.5			0.4	
	V _{OL} (7)	• Ports 7, 8	I _{OI} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (8)	• XT2	I _{OL} =1mA	2.2 to 5.5			0.4	
	V _{OL} (9)	Ports A, B, C, D	I _{OH} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (10)		I _{OL} =1mA	2.2 to 5.5			0.4	
LCD output voltage deviation	VODLS	S0 to S31	I _O =0mA VLCD, 2/3VLCD 1/3VLCD level output See Fig. 8.	2.2 to 5.5	0		±0.2	
	VODLC	COM0 to COM3	I _O =0mA VLCD, 2/3VLCD 1/2VLCD, 1/3VLCD level output See Fig. 8.	2.2 to 5.5	0		±0.2	
LCD bias resistor	RLCD(1)	Resistance per one bias resister	See Fig. 8.	2.2 to 5.5		60		
	RLCD(2)	Resistance per one bias resister 1/2 resistance mode	See Fig. 8.	2.2 to 5.5		30		kΩ

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Davasatas	O. mala al	Pin/Remarks	O a maliki a ma		Specification			
Parameter	Symbol		Conditions	V _{DD} [V]	min	typ	max	unit
Pull-up MOS Tr.	Rpu(1)	• Ports 0, 1, 3, 7	V _{OH} =0-9V _{DD}	4.5 to 5.5	15	35	80	1.0
resistance	Rpu(2)	• Ports A, B, C, D		2.2 to 4.5	18	50	150	kΩ
Hysteresis voltage	VHYS(1)	• Ports 1, 7 • RES		2.2 to 5.5		0.1V _{DD}		V
	VHYS(2)	Port 87 small signal input side		2.2 to 5.5		0.1V _{DD}		V
Pin capacitance	CP	All pins	V _{IN} =V _{SS} for pins other than that under test f=1MHz Ta=25°C	2.2 to 5.5		10		pF
Input sensitivity	Vsen	Port 87 small signal input side		2.2 to 5.5	0.12V _{DD}			Vp-p

Serial I/O Characteristics at Ta = -20° C to $+85^{\circ}$ C, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V

1. SIO0 Serial I/O Characteristics (Note 4-1-1)

		Parameter	Symbol	Pin/Remarks	Conditions			Specif	cation	
		rarameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(1)	SCK0(P12)	See Fig. 6.		2			
	X	Low level pulse width	tSCKL(1)				1			
	Input clock	High level pulse width	tSCKH(1)			2.2 to 5.5	1			+0)/0
Serial clock			tSCKHA(1)		Continuous data transmission/reception mode See Fig. 6. (Note 4-1-2)		4			tCYC
Serial		Frequency	tSCK(2)	SCK0(P12)	CMOS output selected See Fig. 6.		4/3			
	ock	Low level pulse width	tSCKL(2)					1/2		tSCK
	Output clock		tSCKH(2)			2.2 to 5.5	1/2			
	O		tSCKHA(2)		Continuous data transmission/reception mode CMOS output selected See Fig. 6.		tSCKH(2) +2tCYC		tSCKH(2) +(10/3) tCYC	tCYC
Serial input		ta setup time	tsDI(1)	SB0(P11), SI0(P11)	Must be specified with respect to rising edge of SIOCLK	0.0155	0.03			
Serial	Da	ta hold time	thDI(1)		• See Fig. 6.	2.2 to 5.5	0.03			
	clock	Output delay time	tdDO(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode (Note 4-1-3)				(1/3)tCYC +0.05	μs
loutput	Serial output Output clock	tdDO(2)		Synchronous 8-bit mode (Note 4-1-3)	2.2 to 5.5			1tCYC +0.05		
Seria			tdDO(3)		(Note 4-1-3)				(1/3)tCYC +0.05	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous transmission/reception mode, a time from SI0RUN being set when serial clock is "H" to the first falling edge of the serial clock must be longer than tSCKHA.

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 6.

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

	_		O. made al	Dia/Damada	O and this are			Speci	fication	
	Р	arameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	¥	Frequency	tSCK(3)	SCK1(P15)	See Fig.6.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.2 to 5.5	1			
clock	'n	High level pulse width	tSCKH(3)				1			tCYC
Serial clock	충	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected See Fig. 6.		2			
	Low level pulse width		tSCKL(4)			2.2 to 5.5	1/2			tSCK
		High level pulse width	tSCKH(4)					1/2		ISCK
input	Data setup time Data hold time Output delay time		tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK. See Fig. 6.		0.03			
Serial			thDI(2)			2.2 to 5.5	0.03			
Serial output			tdDO(4)	SO1(P13), SB1(P14)	Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 6.	2.2 to 5.5			(1/3)tCYC +0.05	μѕ

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

Pulse Input Conditions at $Ta = -20^{\circ}C$ to $+85^{\circ}C$, VSS1 = VSS2 = VSS3 = 0V

	0	D' - /D 1 -	0 - 171			Spe	cification	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level pulse width	tPIH(1) tPIL(1)	INT0(P70), INT1(P71), INT2(P72)	Interrupt source flag can be set.Event inputs for timer 0 are enabled.	2.2 to 5.5	1			
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	Interrupt source flag can be set.Event inputs for timer 0 are enabled.	2.2 to 5.5	2			
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	Interrupt source flag can be set.Event inputs for timer 0 are enabled.	2.2 to 5.5	64			tCYC
	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	Interrupt source flag can be set.Event inputs for timer 0 are enabled.	2.2 to 5.5	256			
	tPIH(5) tPIL(5)	MICIN(P87)	The pulses can be counted by the small signal sensor/counter.	2.2 to 5.5	1			
	tPIL(6) signals		The pulses can be recognized as signals by the infrared remote control receiver circuit.	2.2 to 5.5	3			RMCK (Note5-1)
	tPIL(7)	RES	Resetting is enabled.	2.2 to 5.5	2000			μs

Note 5-1: RMCK denotes the frequency of the base clock (1tCYC to 128tCYC/subclock source oscillation frequency) for the infrared remote control receiver circuit

AD Converter Characteristics at $V_{SS}1 = V_{SS}2 = 0V$

<12bits AD Converter Mode at Ta =-30 to +70°C>

D	0	D' - /D 1 -	O Hits		Specification				
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
Resolution	N	AN0(P80)		3.0 to 5.5		12		bit	
Absolute accuracy	ET	to AN7(P87), AN8(P70),	(Note 6-1)	3.0 to 5.5			±16	LSB	
Conversion	tCAD	AN9(P71),	See conversion time calculation	4.0 to 5.5	32		100		
time		AN10(XT1), AN11(XT2)	formulas. (Note 6-2)	3.0 to 5.5	40		100	μs	
Analog input voltage range	VAIN				V _{SS}		v_{DD}	٧	
Analog port	IAINH		VAIN=V _{DD}				1		
input current	IAINL		VAIN=V _{SS}	5	-1			μΑ	

<8bits AD Converter Mode at Ta =-30 to +70°C>

Davisariation	O. made al	Dia/Damarda	O and divisor a			Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P80)		3.0 to 5.5		8		bit
Absolute accuracy	ET	to AN7(P87), AN8(P70),	(Note 6-1)	3.0 to 5.5			1.5	LSB
Conversion	tCAD	AN9(P71), AN10(XT1) AN11(XT2)	See "Conversion time calculation	4.0 to 5.5	20		90	
time			method." (Note 6-2)	3.0 to 5.5	40		90	
			See "Conversion time calculation method." (Note 6-2) Ta=-10 to 50°C	3.0 to 5.5	V _{SS}		V _{DD}	μs
Analog input voltage range	VAIN			3.0 to 5.5			1	V
Analog port	IAINH		VAIN=V _{DD}	3.0 to 5.5	-1			
input current	IAINL		VAIN=V _{SS}	3.0 to 5.5	-1			μА

<Conversion time calculation method>

12bits AD Converter Mode: tCAD (conversion time) = $((52/(\text{division ratio})) + 2) \times (1/3) \times \text{tCYC}$ 8bits AD Converter Mode: tCAD (conversion time) = $((32/(\text{division ratio})) + 2) \times (1/3) \times \text{tCYC}$

<Recommended Operating Conditions>

External	Supply Voltage	System Clock	Cycle Time	AD Frequency	Conversion Time (tCAD)[μs]		
oscillator FmCF[MHz]	Range V _{DD} [V]	Division (SYSDIV)	tCYC [ns]	Division Ratio (ADDIV)	12-bit AD	8-bit AD	
10	4.0 to 5.5	1/1	250	1/8	34.8	21.5	
12	3.0 to 5.5	1/1	250	1/16	69.5	42.8	

Note 6-1: The quantization error (±1/2LSB) is excluded from the absolute accuracy value. The absolute accuracy refers to the accuracy that is measured while there is no change in the I/O state of the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the interval from the time the instruction for starting the converter is issued till the time the complete digital- conversion-value corresponding to the analog input value is loaded in the required register.

$\textbf{Consumption Current Characteristics} \ \, \text{at Ta} = -20^{\circ}\text{C to} \ \, +85^{\circ}\text{C}, \ \, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V_{SS} = 0.$

Parameter	Symbol	Pin/Rema	Conditions			Specific	cation	
Farameter	Symbol	rks	Conditions	V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	FmCF=12MHz ceramic oscillation mode FmX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		8.2	18.0	
(Note 7-1)	IDDOP(2)		Internal RC oscillation stopped Multifrequency RC oscillation stopped 1/1 frequency division ratio	3.0 to 3.6		4.8	10.6	
	IDDOP(3)		FmCF=8MHz ceramic oscillation mode FmX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		6.4	13.9	
	IDDOP(4)		System clock set to 8MHz side Internal RC oscillation stopped	3.0 to 3.6		3.8	8.8	
	IDDOP(5)		Multifrequency RC oscillation stopped 1/1 frequency division ratio	2.5 to 3.0		3.0	6.7	
	IDDOP(6)		FmCF=4MHz ceramic oscillation mode FmX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		3.9	8.5	
	IDDOP(7)		System clock set to 4MHz side Internal RC oscillation stopped			2.5	5.2	
	IDDOP(8)		Multifrequency RC oscillation stopped 1/2 frequency division ratio	2.2 to 3.0		2.1	4.3	mA
	IDDOP(9)		FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		0.7	1.6	
	IDDOP(10)		System clock set to internal RC oscillation	3.0 to 3.6		0.4	0.9	
	IDDOP(11)		Multifrequency RC oscillation stopped 1/2 frequency division ratio	2.2 to 3.0		0.3	0.7	
	IDDOP(12)		FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal oscillation mode Internal RC oscillation stopped	4.5 to 5.5		7.6	16.7	
	IDDOP(13)		System clock set to 10MHz multifrequency RC oscillation 1/1 frequency division ratio	3.0 to 3.6		4.3	9.5	
	IDDOP(14)		FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		4.1	8.9	
	IDDOP(15)		Internal RC oscillation stopped System clock set to 4MHz multifrequency	3.0 to 3.6		2.3	5.0	
	IDDOP(16)		RC oscillation • 1/1 frequency division ratio	2.2 to 3.0		2.0	4.1	
	IDDOP(17)		FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		41.8	171.4	
	IDDOP(18)		System clock set to 32.768kHz side Internal RC oscillation stopped Multifrequency RC oscillation stopped 1/2 frequency division ratio			17.7	84.3	μΑ
	IDDOP(19)					13	67.2	

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

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Parameter	Symbol	Pin/	Conditions			Specif	ication	
	,	Remarks		V _{DD} [V]	min	typ	max	unit
HALT mode consumption current	IDDHALT(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	HALT mode • FmCF=12MHz ceramic oscillation • FmX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		3.7	8.2	
(Note 7-1)	IDDHALT(2)		System clock set to 12MHz side. Internal RC oscillation stopped Multifrequency RC oscillation stopped 1/1 frequency division ratio	3.0 to 3.6		1.9	4.3	
	IDDHALT(3)		HALT mode • FmCF=8MHz ceramic oscillation mode	4.5 to 5.5		6.4	13.9	
	IDDHALT(4)		FmX'tal=32.768kHz crystal oscillation mode System clock set to 8MHz side Internal RC oscillation stopped	3.0 to 3.6		3.8	8.8	
	IDDHALT(5)		Multifrequency RC oscillation stopped 1/1 frequency division ratio	2.5 to 3.0		3.0	6.7	
	IDDHALT(6)		HALT mode • FmCF=4MHz ceramic oscillation mode • EmV'tal 22 769kHz graphs accillation mode	4.5 to 5.5		3.9	8.5	
	IDDHALT(7)		FmX'tal=32.768kHz crystal oscillation mode System clock set to 4MHz side Internal RC oscillation stopped	3.0 to 3.6		2.5	5.2	
	IDDHALT(8)		Multifrequency RC oscillation stopped 1/2 frequency division ratio	2.2 to 3.0		2.1	4.3	mA
	IDDHALT(9)		HALT mode FmCF=0Hz (oscillation stopped)	4.5 to 5.5		0.4	0.9	
	IDDHALT(10)		FmX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation	3.0 to 3.6		0.18	0.4	
	IDDHALT(11)		Multifrequency RC oscillation stopped 1/2 frequency division ratio	2.2 to 3.0		0.13	0.3	
	IDDHALT(12)		HALT mode • FmCF=0Hz (oscillation stopped) • FmX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		3.4	7.3	
	IDDHALT(13)		Internal RC oscillation stopped System clock set to 10MHz multifrequency RC oscillation 1/1 frequency division ratio	3.0 to 3.6		1.7	3.7	
	IDDHALT(14)		HALT mode • FmCF=0Hz (oscillation stopped)	4.5 to 5.5		1.7	3.9	
	IDDHALT(15)		FmX'tal=32.768kHz crystal oscillation mode Internal RC oscillation stopped System clock set to 4MHz multifrequency RC	3.0 to 3.6		0.8	1.8	
	IDDHALT(16)		oscillation • 1/1 frequency division ratio	2.2 to 3.0		0.6	1.4	
	IDDHALT(17)		HALT mode • FmCF=0Hz (oscillation stopped)	4.5 to 5.5		25.7	141.9	
	IDDHALT(18)		FmX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side Internal RC oscillation stopped	3.0 to 3.6		8.3	66.6	
HOLD mode consumption	IDDHALT(19)		Multifrequency RC oscillation stopped 1/2 frequency division ratio	2.2 to 3.0		5.2	52.3	_
	IDDHOLD(1)	V _{DD} 1	HOLD mode	4.5 to 5.5		0.14	28.0	μΑ
	IDDHOLD(2)	_	• CF1=V _{DD} or open	3.0 to 3.6		0.03	19.0	
urrent	IDDHOLD(3)	<u> </u>	(external clock mode)	2.2 to 3.0		0.03	16.0	
Clock	IDDHOLD(4)	V _{DD} 1	Clock HOLD mode	4.5 to 5.5		21.9	80	
HOLD mode	IDDHOLD(5)	1	• CF1=V _{DD} or open	3.0 to 3.6		6.3	37	
consumption	IDDHOLD(6)	1	(external clock mode) • FmX'tal=32.768kHz crystal oscillation mode	2.2 to 3.0		3.6	30	

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Davamatan	Symbol	I Pin/Remarks	O a malikia ma		Specification			
Parameter	Symbol		Conditions	V _{DD} [V]	min	typ	max	unit
Onboard programming current	IDDFW(1)	V _{DD} 1	128-byte programming Erasing current included	3.0 to 5.5				mA
Programming time	tFW(1)		128-byte programmingErasing current includedTime for setting up 128-byte data is excluded.	3.0 to 5.5				ms

UART (Full Duplex) Operating Conditions at Ta = -20 to +85°C, VSS1 = VSS2 = VSS3 = 0V

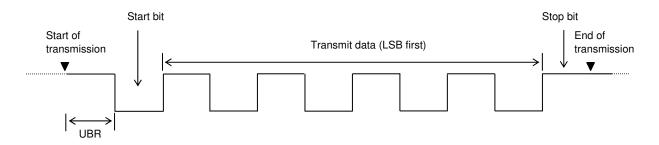
Dawasatan	O. mada ad	Symbol Pin/Remarks	O a madiki a ma		Specification				
Parameter	Symbol		Conditions	V _{DD} [V]	min	typ	max	unit	
Transfer rate	UBR	UTX(P00), URX(P01)		2.2 to 5.5	16/3		8192/3	tCYC	

Data length: 7/8/9 bits (LSB first)

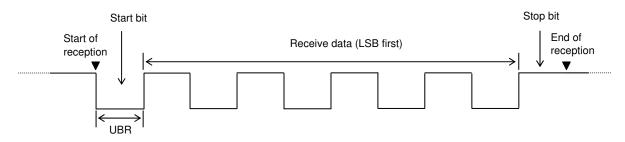
Stop bits: 1 bit (2-bit in continuous data transmission mode)

Parity bits: None

Example of 8-bit Data Transmission Mode Processing (Transmit Data=55H)



Example of 8-bit Data Reception Mode Processing (Receive Data=55H)



*When using UART, set POLDDR (PODDR: Bit0) to "0"

Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a SANYO-designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1	Characteristics	of a Sample	Main Sv	stem Clock	Oscillator (Circuit with a	Ceramic Oscillator
I dole 1	Ciluitacteribules	or a builtpi	o iviaili o y	bicin Ciock	Obciliator	Chican while a	Ceramic Oscillator

Nominal	Vendor	Oscillator Name	Circuit Constant		Operating Voltage	Oscillation Stabilization Time		Remarks			
Frequency Name		Oscillator Name	C1 [pF]	C2 [pF]	Rf1 [Ω]	Rd1 [Ω]	Range [V]	typ [ms]	max [ms]	nemarks	
12MHz	MURATA	CSTCE12M0G52-R0	(10)	(10)	Open	2.2k	2.8 to 5.5			Built-in C1, C2	
OMI I-	MUDATA	CSTCE8M00G52-R0	(10)	(10)	Open	1.0k	054-55			Built-in	
8MHz	MURATA	CSTLS8M00G52-R0	(15)	(15)	Open	1.0k	2.5 to 5.5			C1, C2	
4841.1-	MURATA	CSTCR4M00F53-R0	(15)	(15)	Open	2.2k	0.1 to F.F.			Built-in C1, C2	
4MHz		CSTLS4M0053-B0	(15)	(15)	Open	2.2k	2.1 to 5.5				

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Figure 4).

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a SANYO-designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

Nominal Frequency	Vendor Name	Oscillator Name	Circuit Constant				Operating	Oscillation Stabilization Time		Damada
			C3	C4	Rf2	Rd2	Voltage Range [V]	typ	max	Remarks
			[pF]	[pF]	$[\Omega]$	$[\Omega]$	[v]	[s]	[s]	
32.768kHz										

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HOLD mode is reset (see Figure 4).

Caution: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

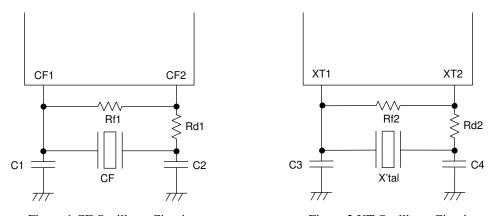
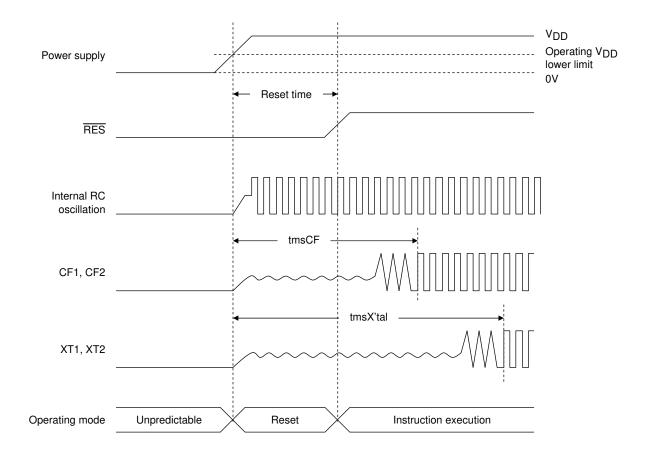


Figure 1 CF Oscillator Circuit

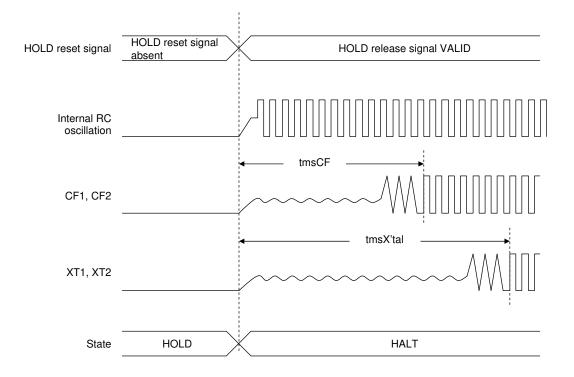
Figure 2 XT Oscillator Circuit



Figure 3 AC Timing Measurement Point

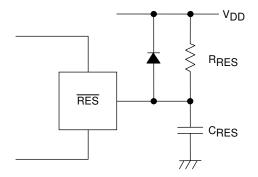


Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Times



Note:

Determine the value of C_{RES} and R_{RES} so that the reset signal is present for a period of 200 μ s after the supply voltage goes beyond the lower limit of the IC's operating voltage.

Figure 5 Reset Circuit

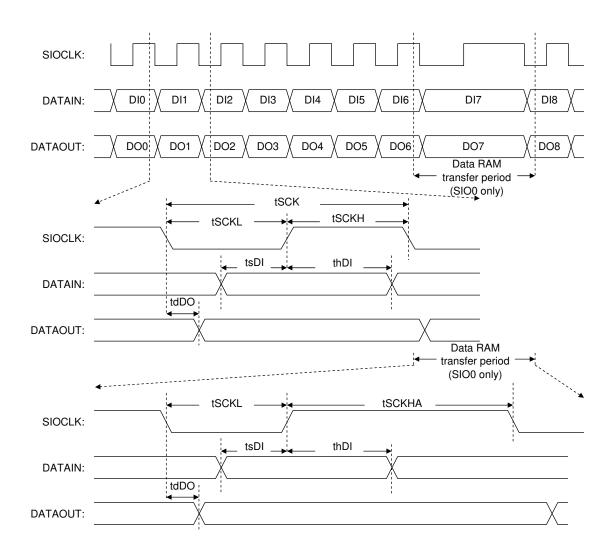


Figure 6 Serial I/O Waveforms

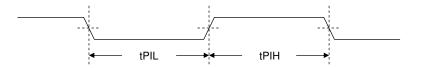


Figure 7 Pulse Input Timing Signal Waveform

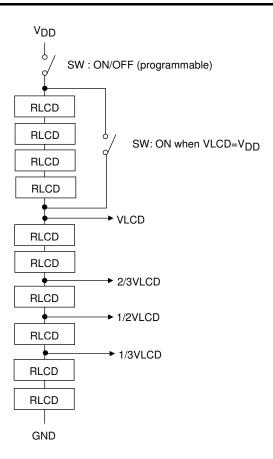


Figure 8 LCD Bias Resistors

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